ABSTRACT OF THE DISCLOSURE

MOLDED STIFFENER FOR FLEXIBLE CIRCUIT MOLDING

A molded flexible circuit assembly and method of forming a molded flexible circuit assembly which use a molded stiffener, and do not require any additional type of stiffener, are described. A molded stiffener is formed on a flexible tape at the same time molded encapsulation units are formed to encapsulate circuit die which are attached to the flexible tape. The molded stiffeners provide adequate rigidity for processing of the molded flexible circuit assembly. When the stiffeners are no longer needed they are removed at the same time the mold runners are removed. No additional processing steps are required for either the formation or removal of the molded stiffeners.

(FIGURE 3 IS SUGGESTED FOR PUBLICATION)